

mSSD IDEP 2.5" and 3.5"

60nm Flash Process Support

Product Update, August 2006

1. Description

The mSSD™ IDEP 2.5" and 3.5" (formerly known as FFD 2.5" and 3.5" IDE Plus) offer support for the SLC NAND flash components that are manufactured using the 60 nm process, now commonly available in today's market.

No changes were made to the mSSD IDEP 2.5" and 3.5" product specifications.

1.1 Ordering Information

The ordering information is listed in Table 1 and Table 2 below:

Table 1: Ordering Information for mSSD IDEP 2.5"

FFD-25-IDEP-CCCC-T-H		
CCCC	Unformatted capacity (MB)	512, 1024, 2048, 4096, 6144, 8192, 10240, 12288, 16384, 20480, 24576, 28672, 32768, 36864, 40960, 43008, 45056
T	Temperature range	Blank: Commercial 0°C - +70°C N: Enhanced -25°C - +75°C X: Extended -40°C - +85°C
H	Case height	A: 8.5 mm up to 4GB B: 11.3 mm up to 12GB C: 14.3 mm up to 24GB D: 18.5 mm up to 36GB F: 26.6 mm up to 45GB

Table 2: Ordering Information for mSSD IDEP 3.5"

FFD-35-IDEP-CCCC-T		
CCCC	Unformatted density (MB)	512, 1024, 2048, 4096, 6144, 8192, 10240, 12288, 16384, 20480, 24576, 28672, 32768, 36864
T	Temperature range	Blank: Commercial 0°C - +70°C N: Enhanced -25°C - +75°C X: Extended -40°C - +85°C
	Case height	25.4 mm up to 36GB

2. Reason for Change

As flash components manufactured with the new 60 nm process have become more widely available in the market today, flash components manufactured with the older processes are being phased out of the market, and as a result are subject to lower availability.

2.1 Availability

The mSSD IDEP 2.5" and 3.5" will be manufactured with the new flash process from September 2006.

3. How to Contact Us

Please contact your msystems representative or visit the Embedded Systems section on the msystems website (www.m-systems.com) for any further information or assistance.

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